Market Place

Topic 2: Plated contacts: are we getting any closer to mass-adooption in production?

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Different rear side metallization technologies

IBC / Sunpower

Different front side metallization technologies

HJT / PERC
Copper plating

- No cost nor technological pressure to replace screen printing on PERC
- Maybe opportunity with TOPCON / passivated contact
  Ag pastes still in development
- Technological need to switch to plating
  - IBC: high line conductivity necessary
  - HJT: high paste consumption especially for bifacial cell / low temperature paste is expensive
- Opportunity for temperature sensitive cells like PK / tandems
- Shingling: reduction of cell segments
Ag price may increase

2019: 20.25% x 0.987 (CTM) ≈ 4.91 W/ cell *
→ ≈ 18.3 t / GWp
→ ≈ 18300 t @100GW = 6.3 % of world Silver market 2017**
Medium scenario

500 GWp in 2025

=> Silver consumption for PV approximately 30% of global production